

# APPROVAL SHEET

# MULTILAYER CERAMIC CAPACITOR Automotive Grade, Soft Termination Type (AEC-Q200 Qualified)

Approved by customer : (signing or stamping here)								

SAMV	SAMWHA CAPACITOR CO., LTD.							
Prepared by	Prepared by Checked by Approved by							
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2020. 05. 26.

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< SPECIFICATION SUMMARY >								
SAMWHA Part no.	CQ3225X7R106K500ARL							
Туре	*MLCC for Automotive Application							
Items	Specification	Test Conditions						
Capacitance	10	μF	Testing Frequency: 1 ±0.1 kHz					
Capacitance Tolerance	± 10	%	Testing Voltage : 1 ±0.2 Vrms					
Dissipation Factor	Max. 12.5	%	Should be measured at 25 ℃.					
Insulation Resistance	Min. 5	MΩ	Should be measured with a DC voltage not exceeding rated voltage at 25℃ for 2 minutes of charging.					
	3.20 ±0.50	L (mm)	Capacitance Tolerance Code page 1/9					
Chip Size	2.50 ±0.30	W (mm)	Chip size page 2/9					
	2.50 ±0.30	T (mm)	Characteristics & Test Method page 3/9~6/9					
*Thin Layer Large-Capacitance Type								

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Enactment :
Feb. 1, 2010

MULTILAYER CERAMIC CAPACITOR
Automotive Grade, Soft Termination Type

NO SW - Q - 01A

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\*Caution: Reflow soldering only

#### 1. General Code

#### (1) Type Designation

CQ	3225	<u>X7R</u>	<u>106</u>	K	<u>500</u>	<u>A</u>	R	<u>L</u>
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Automotive Grade)
- 2) Size Code:

This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

#### 3) Temperature Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class	C0G	-55 to +125℃	±30 ppm/℃
	X7R	-55 to +125℃	±15%
Class	X7S	-55 to +125℃	±22%
Class II	X7T	-55 to +125℃	+22% ~ -33%
	X6S	-55 to +105℃	±22%

#### 4) Capacitance Code(Pico farads):

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero ex)  $104 = 100000 \, pF$ 

R denotes decimal

8R2 = 8.2 pF

#### 5) Capacitance Tolerance Code

Code	Tolerance		
В	± 0.1 pF		
С	± 0.25 pF		
D	± 0.5 pF		
F	± 1.0 %		

Code	Tolerance			
G	± 2.0 %			
J	± 5 %			
K	± 10 %			
M	± 20 %			

#### 6) Voltage Code

Code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
Rated	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Voltage	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

#### 7) Termination Code

N: Nickel-Tin Plate

A: Nickel-Tin Plate -> Soft Termination Type

#### 8) Packing Code

R: 7" Reel Type, L: 13" Reel Type, B: Bulk Type

#### 9) Thickness option

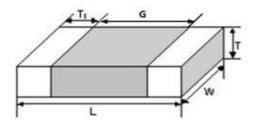
Thickne	ess (mm)	Codo	Thickne	ss (mm)	Code
t	Tol(±)	Code	t	Tol(±)	Code
0.50	0.10	Blank	1.35	0.20	Н
0.60	0.10	А	1.60	0.30	I
0.80	0.15	В	1.80	0.30	J
0.85	0.15	В	2.00	0.30	K
1.00	0.15	Е	2.50	0.30	L
1.10	0.15	Е	2.80	0.30	M
1.15	0.20	Е	3.20	0.40	N
1.25	0.20	Е	5.00	0.50	0
1.30	0.20	Е			

### 2. Temperature Characteristics

See Page 6/9 (No.21)

#### 3. Constructions and Dimensions

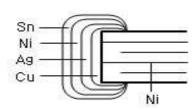
#### (1) Dimensions



		Dimension								
Size Code	Size Code EIA Code		Length			dth	T1(min.)	0( : )		
		L	Tol(-)	Tol(+)	W	W Tol(±)		G(min.)		
1005	0402	1.00	0.05	0.10	0.50	0.10	0.05	0.30		
1608	0603	1.60	0.15	0.20	0.80	0.15	0.10	0.50		
2012	0805	2.00	0.20	0.30	1.25	0.20	0.10	0.65		
3216	1206	3.20	0.50	0.50	1.60	0.30	0.15	1.00		
3225	1210	3.20	0.50	0.50	2.50	0.30	0.15	1.05		
4520	1808	4.50	0.50	0.50	2.00	0.30	0.20	1.50		
4532	1812	4.50	0.50	0.50	3.20	0.40	0.20	1.50		
5750	2220	5.70	0.30	0.70	5.00	0.50	0.30	1.85		

(Unit: mm)

#### (2) Construction of Termination



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## Specifications and Test Methods (For Automotive Applications)

Na	AEC-Q200		Spec	cification	Test Methods and Conditions			
No.	Test	Item	Class I	Class II	Test Methods and Conditions			
Pre-and Post-Stress Electrical Test					-			
		Appearance	No defects which may affect	performance				
	'		Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0% (*Within ±12.5%)	─ Temperature : Max. operating temperature±3 °C			
2	Temperature Exposure (Storage)	Q/D.F.	30pF min.: Q≥1000 30pF max.: Q≥400+20xC C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Maintenance Time: 1000+48/-0 hrs  Let sit for 24±2 hours at room temperature, then measure.			
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ (Whichever is smaller)	P-F (*50Ω·F)				
		Appearance	No defects which may affect	performance	Perform the 1000 cycles according to the four heat treatments			
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0%	listed in the following table.  Let sit for 24±2 hours at room temperature, then measure.			
3	Temperature		30pF min.:Q≥1000	Rated Voltage 16V min.: 0.05 max.				
	Cycle	Q/D.F.	30pF max.:Q≥400+20xC	10V: 0.075 max.	Temp.(°C) -55+0/-3 25±2 125+3/-0 25±2 Time(min) 15±3 1 15±3 1			
		I.R.	C: Nominal Capacitance (pF)  More than $10,000M\Omega$ or $500\Omega$ (Whichever is smaller)	*0.2 max. PF (*50Ω·F)	Initial measurement Perform the initial measurement according to Note 1 for Class II.			
4	Destructive Physical Anal	ysis	No defects or abnormalities		Per EIA-469			
		Appearance	No defects which may affect	performance	Temperature : 25~65℃, Humidity : 80~98%			
		Capacitance Change	Within ±3.0% or±0.30pF (Whichever is larger)	Within ±12.5%	Cycle Time: 24 hrs/cycle, 10 cycles  Let sit for 24±2 hours at room temperature, then measure.  80-98%  80-98%  80-98%  80-98%  80-98%  80-98%  80-98%  80-98%  80-98%			
5	Moisture Resistance	Q/D.F.	30pF min.: Q≥350 10pF min. and 30pF max.: Q≥275+5/2×C 10pF max.: Q≥200+10×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	60 55 (c) 45 en 35 en 35 en 25 en 20			
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ (Whichever is smaller)	P-F (*50Ω-F)	15 10 5 0 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 Time(hrs)			
		Appearance	No defects which may affect	performance				
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	Temperature: 85±3°C Humidity: 80~85%			
6	Biased Humidity	Q/D.F.	30pF min.: Q≥200 30pF max.: Q≥100+10/3×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Maintenance Time: 1000+48/-0 hrs Let sit for 24±2 hours at room temperature, then measure.			
		I.R.	More than 1,000M $\Omega$ or 50 $\Omega$ ·F (Whichever is smaller)	(*5Ω·F)	The charge/discharge current is less than 50mA.			
		Appearance	No defects which may affect	performance				
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	Temperature : Max. operating temperature±3 °C  Applied Voltage : Rated Voltage × 200% (*100%)  Maintenance Time : 1000+48/-0 hrs			
7	Operational Life	Q/D.F.	30pF min.:Q≥350 10pF min. and 30pF max.: Q≥275+5/2×C 10pF max.: Q≥200+10×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Let sit for 24±2 hours at room temperature, then measure.  The charge/discharge current is less than 50mA.  Initial Measurement for Class II  Applied 200% of the rated voltage for one hour at 125±3°C.  Remove and let sit for 24±2 hours at room temperature, then			
		I.R.	More than 1,000M $\Omega$ or 50 $\Omega$ ·F (Whichever is smaller)	(*5Ω·F)	measure.			

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## Specifications and Test Methods (For Automotive Application)

	AEC-Q200		Specif	fication		Test Methods and Conditions				
No.		Item	Class I	Class	II	Test Methods and Conditions				
8	External Visual		No defects or abnormalities		Visual inspection					
9	Physical Dime	ension	Within the specified dimensions		Using calipers					
		Appearance	No defects which may affect p	erformance						
		Capacitance Change	Within the specified tolerance							
10	Resistance to Solvents	Q/D.F.	30pF min.: Q≥1000 30pF max.: Q≥400+20xC C: Nominal Capacitance (pF)	16V: ( 10V: ( *0.125 max.	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Per MIL-STD-202 Method 215				
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ -F (Whichever is smaller)	· (*50Ω·F)						
		Appearance	No defects which may affect p	erformance						
		Capacitance Change	Within the specified tolerance		Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks)					
11	Mechanical Shock	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V: (	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Test Pulse Wave form : Half-sine Duration : 0.5ms Peak value : 1,500G				
		I.R.	More than $10,000M\Omega$ or $500\Omega$ -F (Whichever is smaller)			Velocity change : 4.7m/s				
		Appearance	No defects or abnormalities							
		Capacitance Change	Within the specified tolerance			The specimens should be subjected to a simple harmonic motion				
12	Vibration	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V: (	0.025 max. 0.03 max. 0.035 max. 0.05 max.	having a total amplitude of 1.5mm. The entire frequency range of 10 to 2,000 Hz and return to 10 Hz should be traversed in 20 minutes. This cycle should be performed 12 times in each of three mutually perpendicular directions (total of 36 times).				
		I.R.	More than $10,000M\Omega$ or $500\Omega$ -F (Whichever is smaller)			-				
		Appearance	No defects which may affect p	erformance						
		Capacitance Change	Within the specified tolerance			Temperature (Eutectic solder solution) : 260±5℃				
13	Resistance to Soldering Heat	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V: (	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Dipping Time: 10±1s Let sit for 24±2 hours at room temperature, then measure.  Initial measurement Perform the initial measurement according to Note 1 for Class II.				
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ -F (Whichever is smaller)							
		Appearance	No defects which may affect p	erformance		Perform the 300 cycles according to the two heat treatments listed				
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±15.0%		in the following table.  Transfer Time: 20sec. max.				
14	Thermal Shock	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V: (	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Let sit for 24±2 hours at room temperature, then measure.         Step       1       2         Temp.(°C)       -55+0/-3       125+3/-0         Time(min.)       15±3       15±3				
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ -F (Whichever is smaller)			Initial measurement Perform the initial measurement according to Note 1 for Class II.				

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Specifications and Test Methods (For Automotive Application)

1	1			Section	T					
No.	AEC-Q200 Test Item		Class	fication Class II	Test Methods and Conditions					
		Appearance	No defects which may affect pe	erformance						
		Capacitance Change	Within the specified tolerance							
15	ESD	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max.	Per AEC-Q200-002					
		I.R.	More than $10,000M\Omega$ or $500\Omega$ -F	(*50Ω·F)	1					
		1.17.	(Whichever is smaller)							
16	Solderability		95% of the terminations is to be s	oldered evenly and continuously.	<ul> <li>(a) Preheat at 155°C for 4 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5°C.</li> <li>(b) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5°C.</li> <li>(c) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 120±5 seconds at 260±5°C.</li> </ul>					
		Appearance	No defects or abnormalities		The capacitance/Q/D.F. should be measured at 25 °C at the					
		Capacitance Change	Within the specified tolerance		frequency and voltage shown in the table.  Class Capacitance (C) Frequency Voltage  C<1000pF 1±0.1MHz 0.5~5Vrms					
17	Electrical Characteriza- tion	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20×C C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max.	Class I  C≥1000pF  1±0.1kHz  1±0.2Vrms  C≤10µF  1±0.1kHz  0.5~1.0Vrms  C>10µF  120±24Hz  0.5±0.1Vrms  Initial measurement  Perform the initial measurement  according to Note1 for Class II  Measurement after test  Take it out and set it for 24±2 hours (Class II)  then measure					
		I.R. at 25℃	More than 100,000M $\Omega$ or 1,000 $\Omega$ -F (Whichever is smaller)	More than 10,000MΩ 500Ω-F (*50Ω-F) (Whichever is smaller)	Should be measured with a DC voltage not exceeding rated					
		I.R. at 125℃	More than 10,000M $\Omega$ or 100 $\Omega$ ·F (Whichever is smaller)	More than 1,000MΩ or $10Ω$ -F (*1 $Ω$ -F) (Whichever is smaller)	voltage at 25°C and 125°C for 2 minutes of charging.					
		Dielectric Strength	No dielectric breakdown or mecha	anical breakdown	Applied 250% of the rated voltage for 1~5 seconds The charge/discharge current is less than 50mA.					
		J	No defects which may affect pe	erformance	Apply a force in the direction shown in the following figure for 60±5 seconds.  Support Solder Chip Printed circuit board before testing					
18	Board Flex	Capacitance Change	Within ±5.0% or ±0.5pF (Whichever is larger)	Within the specified tolerance	Printed circuit board under test  Flexure for Class I: 3mm max.  for Class II: 3mm max.  Reflow soldering only					
		Appearance	No defects which may affect pe	rformance	Apply 18N <sup>1)</sup> force in parallel with the test jig for 60±1 seconds.					
19	Terminal Strength		Within ±5.0% or ±0.5pF		<sup>1)</sup> 10N for 1608(EIA:0603) size					
	Guengui	Change	(Whichever is larger)	Within the specified tolerance	2N for 1005(EIA:0402) size					
		-								

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## Specifications and Test Methods (For Automotive Application)

<b>Test</b> Beam Load Te		The chip endure follow Chip Length 2.5mm max.	ving force.		Class II	Apply a force as shown in the following figure.				
Beam Load Te	est	Chip Length	Thickne	es (T)		Apply a force as shown in the following figure.				
Beam Load T€	est			ess (T)						
Beam Load Te	est	2.5mm max.	T<0.4	ess (T) Force		(i) Chip Length: 2.5mm max. (ii) Chip Length: 3.2mm min.				
Beam Load Te	est	2.5mm max.	1 -0.	ōmm	8N	Beam Speed : 0.5mm/s Beam Speed : 2.5mm/s				
			T>0.5mm		20N					
		3.2mm min.	T<1.25mm		15N	Iron Board				
		3.211111 111111.	T≥1	T≥1.25 54.5N						
Capacitance Temperature Characteris- tics	Capacitance Change  Temperature Coefficient  Capacitance Drift	0±30 ppm/℃		X7R: Within ±15% X7S: Within ±22% X6S: Within ±22% X7T: Within +22% ~ -33%		(i) Class I  The temperature coefficient is determined using the capacitance measured in step 3 as a reference. When cycling the temperature sequentially from step 1 through 5, the capacitance should be within the specified tolerance for the temperature coefficient. The capacitance drift is calculated by dividing the differences between the maximum and minimum measured values in steps 1, 3 and 5 by the capacitance value in step 3.  Step 1 2 3 4 5  Temp.(°C) 25±2 -55±3 25±2 125±3 25±2  (ii) Class II  The ranges of capacitance change compared with the 25 °C value over the temperature range from -55 °C to 125 °C.				
T	emperature Characteris-	Change  Temperature Coefficient  Characteris- ics  Capacitance	Change  Temperature Coefficient  Characteris- ics  Capacitance  Unit Temperature Coefficient  Coefficient  Capacitance  Unit Temperature Unit	Change  Temperature Coefficient  O±30 ppm/°C  Characteris- ics  Capacitance  Within ±0.2% or ±0.05pF	Capacitance Change  Capacitance Change  Temperature Coefficient  O±30 ppm/°C  Capacitance Characteris- Coefficient  Capacitance Characteris- Coefficient  Capacitance  Capacitance  Within ±0.2% or ±0.05pF	Capacitance Change  Capacitance Change  Capacitance Coefficient  Capacitance Coefficient  Capacitance Characteris- Coefficient  Capacitance Characteris- Capacitance Capacitance Characteris- Capacitance Capacitance Capacitance  Capacitance  Within ±0.2% or ±0.05pF				

In the case of "\*" is specifications for "Thin Layer Large Capacitance Type"

Note 1. Initial Measurement for Class II

Perform a heat treatment at 150+0/-10°C for one hour, and then let sit for 24±2 hours at room temperature, then measure.

(Unit: mm)

#### **Packing**

- (1) Bulk Packing
  - 1 1000 pcs per polybag
  - ② 5 polybags per inner box
  - 3 10 inner boxes per out box
- (2) Reel Packing
  - ① 8~10 reels per inner box
  - 2 6 inner boxes per out box
- (3) Reel Dimensions



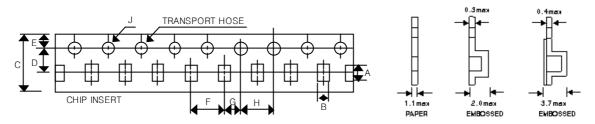


Mark	Size Code	EIA Code	Α	В	С	D	Е	w
7 " Reel	1005~3225	0402~1210	Ф178±2	Ф <b>50Min</b>	Ф13±0.5	Ф21±0.8	2±0.5	10±1.5
	4520~4532	1808~1812	Ф180+0,-3	Ф60-0,+1	Ф13±0.2	Ф57-0+1	3±0.2	13±0.5
13 " Reel	1005~3225	0402~1210	Ф330±2	Φ <b>70Min</b>	Ф13±0.5	Ф21±0.8	2±0.5	10±1.5

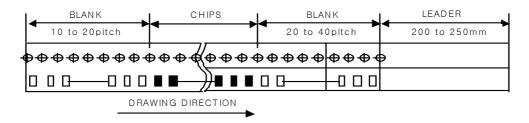
#### (4) Number of Package

Size Code	EIA Code	7"	13"		
Size Code	EIA Code	Quantity(pcs)/Reel	Quantity(pcs)/Reel		
1005	0402	10,000	50,000		
1608	0603	4,000	15,000		
2012	0805	3,000 ~ 4,000	8,000 ~ 15,000		
3216	1206	2,000 ~ 4,000	6,000 ~ 10,000		
3225	1210	1,000 ~ 3,000	4,000 ~ 10,000		
4520	1808	1,500 ~ 3,000	-		
4532	1812	500 ~ 1,000	1,500 ~ 5,000		

#### (5) Tape Dimensions



Size Code	EIA Code	А	В	С	D	E	F	G	Н	J
1005	0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
1608	0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
2012	0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3216	1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3225	1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4520	1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4532	1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1



#### Caution

#### ► Storage Condition

When solderability is considered, capacitor are recommended to be used in 12 months.

(1) Temperature:  $25^{\circ}$ C ±  $10^{\circ}$ C

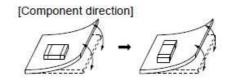
(2) Relative Humidity: Below 70% RH

▶ The Regulation of Environmental Pollution Materials Never use materials mentioned below in MLCC products regulated this document.

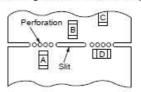
Pb, Cd, Hg, Cr<sup>+6</sup>, PBB(Polybrominated biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos

#### ▶ Mounting Position

Choose a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.



[Chip Mounting Close to Board Separation Point]



Chip arrangement Worst A-C- (B, D) Best

Locate chip

stress acts.

horizontal to the direction in which

#### ► Reflow Soldering

- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference(△T) within the range recommended in Table 1.

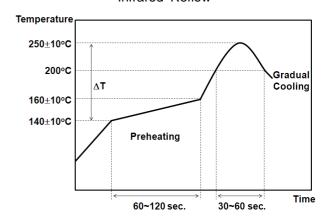
Table 1

Size code (EIA Code)	Temperature Difference
1005~3216 (0402~1206)	△T≤190℃
3225 (1210)	△T≤130°C

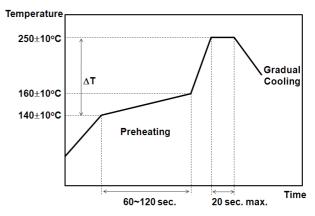
3. Capacitors designated as for only reflow soldering must not apply to wave soldering.

#### Recommended Reflow Soldering Profile for Lead Free Solder

Infrared Reflow



Vapor Reflow



#### Note

▶ 'Aging'/'De-aging' behavior of high dielectric constant type MLCCs (Typically represented by X7R temperature characteristic of which main composition is BaTiO<sub>3</sub>)

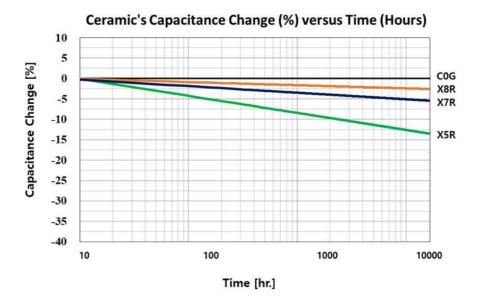
'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric ceramic capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$$C_t = C_{24} (1 - k log 10 t)$$

where,

Ct : Capacitance value, t hours after the start of 'aging' C24 : Capacitance value, 24 hours after its manufacture : Aging constant (capacitance decrease per decade-hour)

: time, in hours, from the start of 'aging'



The capacitance value can be restored (also known as 'de-aged') by exposing the component to elevated temperatures approaching its curie temperature (approximately 120°C). This 'de-aging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing, or by baking at 150°C for about 1 hour.